2SA1700

Rev.E May.-2016

DATA SHEET

/ Descriptions

WR0585 ṂṂ Ł SQS ÆṀ ɥ s ǁ ˥ Silicon PNP transistor in a TO-252 Plastic Package.

/ Features

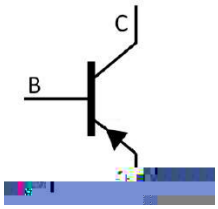
ㄡˋ Ⅵ ɔ ꓤ ı ǁ Ḅ ⓞⓑⓙ ⓦ ˨ ớ ı ㄉ ᗡ ᴗ ᵢ PELW ʻH

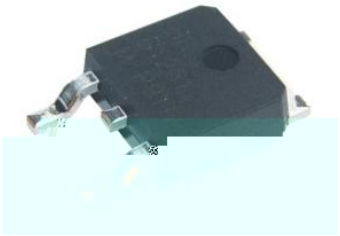
High breakdown voltage, adoption of MBIT process excellent h_{FE} linearity

[redacted]

ᴝ ⌊ ᵢ ᵢ ㄡ ꓤ ᵢ ᴗ

High voltage driver applications.



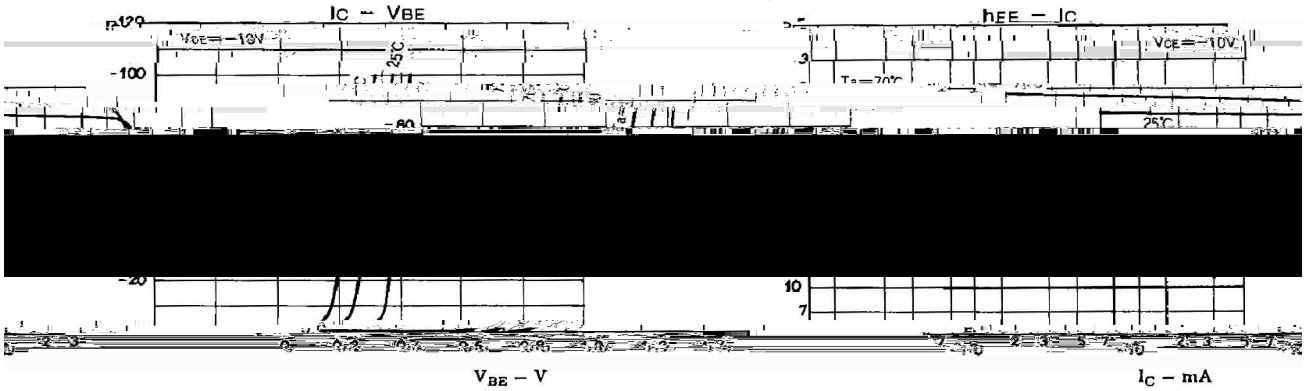


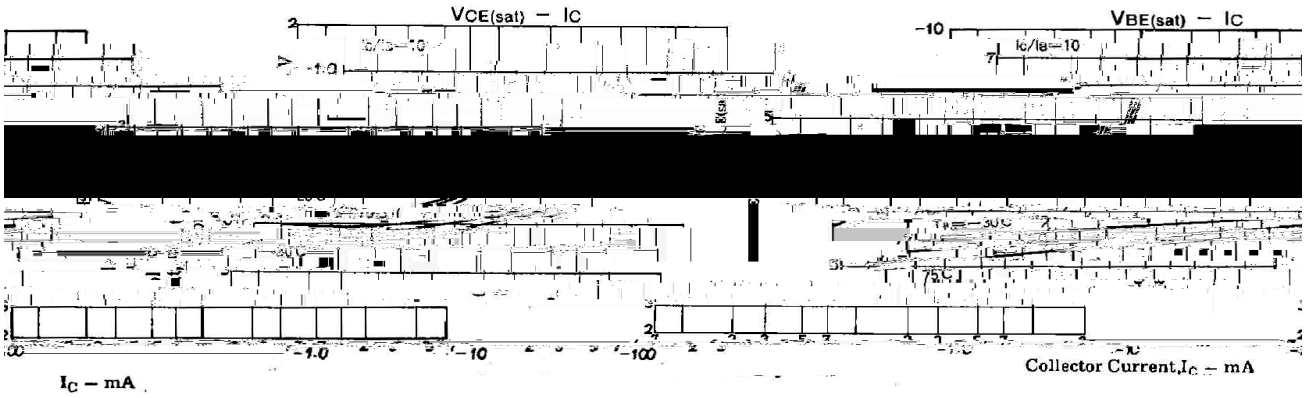
PIN1 χ Base PIN 2,4 χ Collector PIN 3 χ Emitter

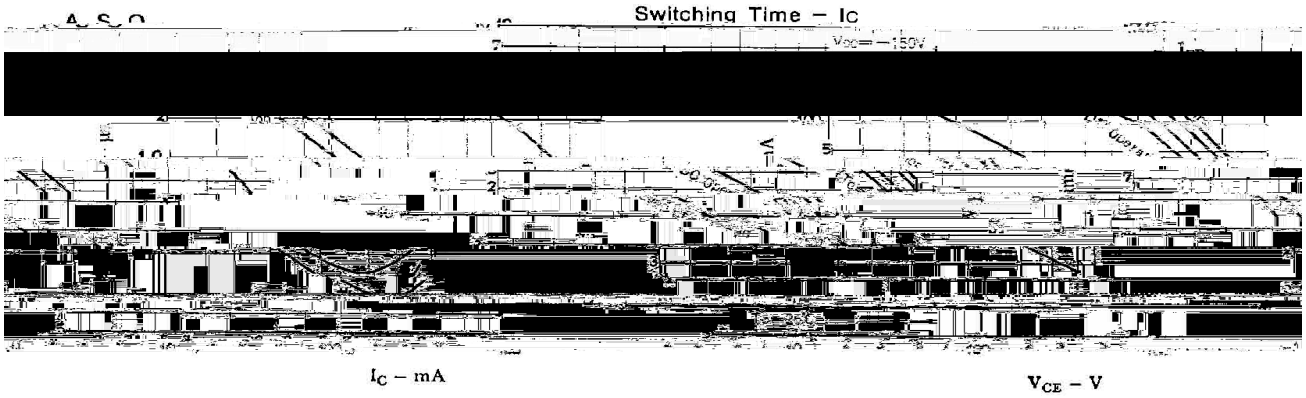
/ h_{FE} Classifications & Marking

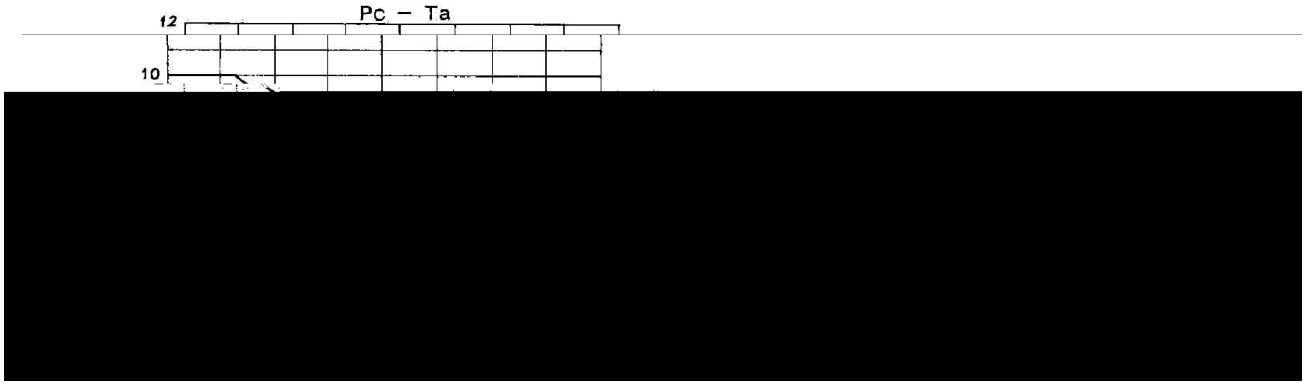
v ̈Ω̣ Parameter	ϟ N Symbol	̈Ω̣Ö Rating	D Ӈ Unit
Collector to Base Voltage	V_{CBO}	-400	V

/ Electrical Characteristic Curve

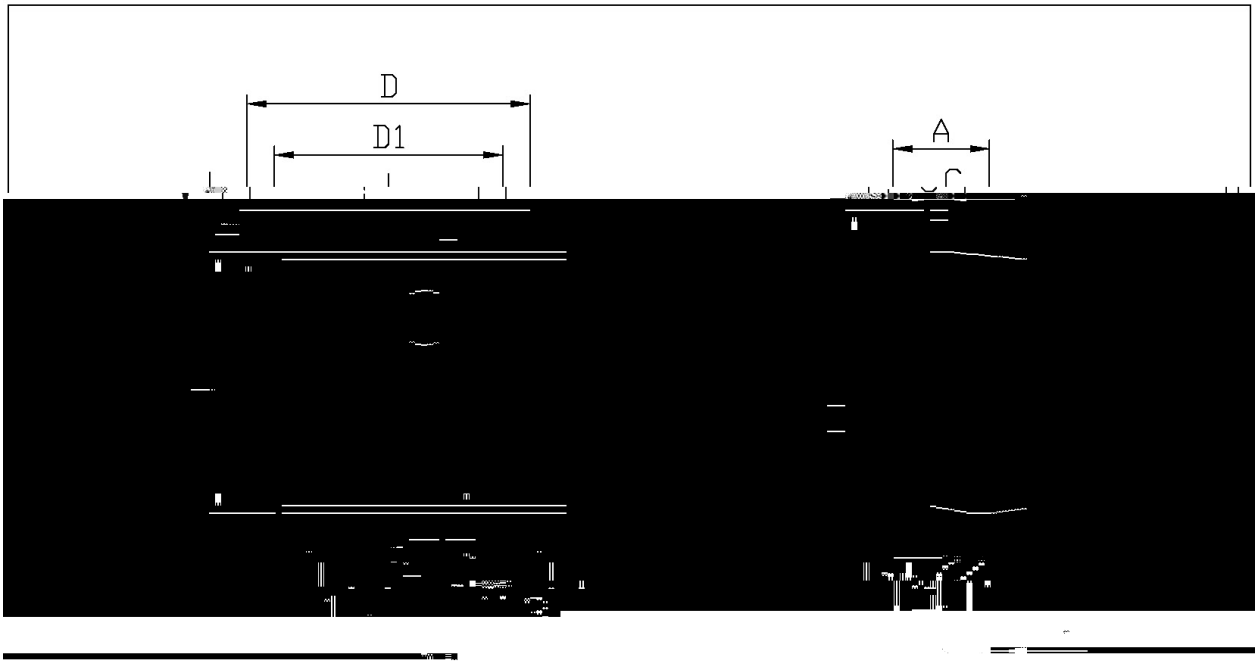






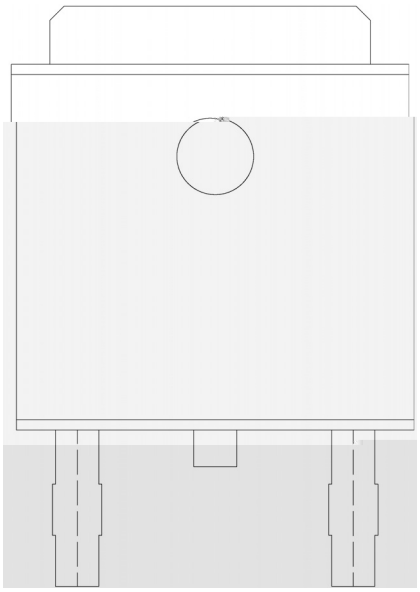


/ Package Dimensions



	4.75				
	0.95	b1	0.45	0.55	L1	0.45
25	1.75	C	0.45	0.55	L2	1.
.60	0.90	D	6.45	6.75	L3	0
0.00	0.10	D1	5.10	5.50	K	

/ Marking Instructions



ب ˝ χ

BR χ ⌘ ⅋ ᴵ Ɱ

A1700 χ ⌘ ⅋ ᴺ Ɱ

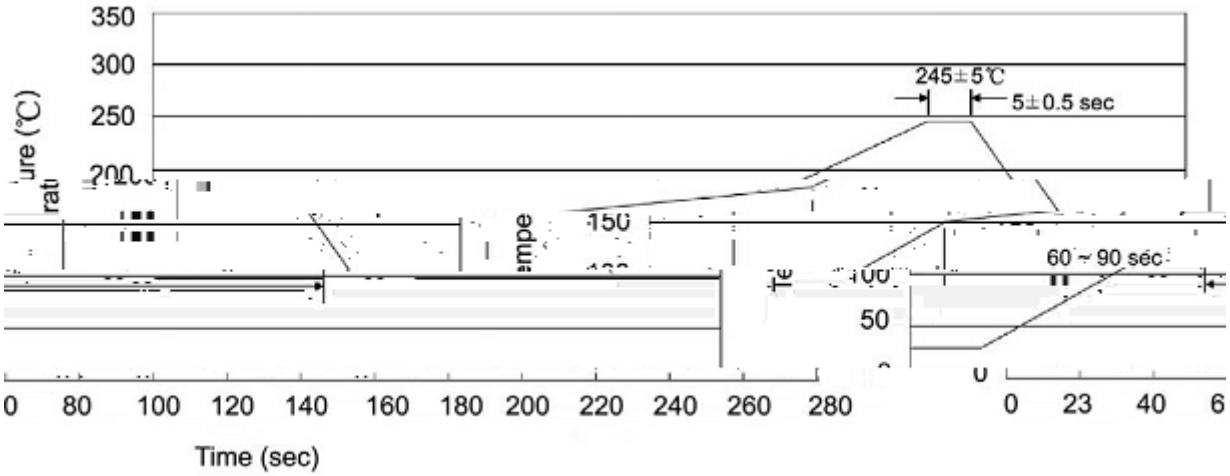
D= ⌘ h_{FE} ʿ ᶠ Ɱ

---- χ ⌘ ⅃ ⅎ ŋ̋ ᴺ Ɱ ⅃ ⅋ ⅃ ⅎ ŋ̋ ᴺ ψ ק

Note:

BR: A13( )Tj22ɸmpanyÀ.OFÖ

( ) / Temperature Profile for IR Reflow Soldering(Pb-Free)



ب ˝ χ

1 ǂ ♬ □ ỷ 25 Ḱ 150 ɫ ı `H ڑ 60 Ḱ 90sec;

2 Š Ö □ ỷ 245 ° 5 ɫ ı `H ڑ ˙Y ⺈ ⺮ 5 ° 0.5sec;

3 ì ˙ ⺈ ˛ ɔ ھ ỷ ⺮ 2 Ḱ 10 ɫ /sec.

Note:

1.Preheating:25~150 ɫ , Time:60~90sec.

2.Peak Temp.:245 ° 5 ɫ , Duration:5 ° 0.5sec.

3. Cooling Speed: 2~10 ɫ /sec.

/ Resistance to Soldering Heat Test Conditions

□ ỷ χ 260 ° 5 ɫ `H ڑ χ 10 ° 1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

ɔ` γ ⊢ / REEL

Package Type	Units	Dimension (unit mm^3)